

ON Semiconductor **10/15/2019**

Base Part		BC636		Pb-free
Orderable Part		BC636TA	Total weight (mg)	223.092
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	0.075	Silicon (Si)	7440-21-3	100
Lead Frame	101.001	Silver (Ag)	7440-22-4	0.9999901
		Manganese (Mn)	7439-96-5	0.49999505
		Nickel (Ni)	7440-02-0	0.18019624
		Iron (Fe)	7439-89-6	97.42477797
		Copper (Cu)	7440-50-8	0.89504064
Mold Compound-Black	112	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8	3
		Ortho Cresol Novolac Resin	29690-82-2	20
		Antimony Trioxide (Sb2O3)	1309-64-4	2.5
		Carbon Black (C)	1333-86-4	0.75
		Fused Silica (SiO2)	60676-86-0	73.75
Plating	9.94	Tin (Sn)	7440-31-5	100
Wire Bond - Au	0.076	Gold (Au)	7440-57-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

<http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF>